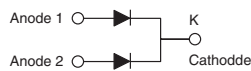
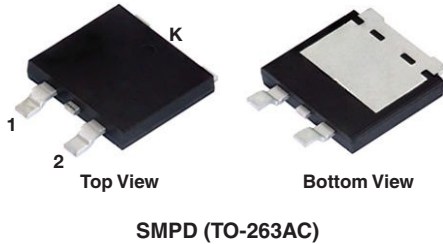


# Dual High Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

## eSMP® Series



## FEATURES

- Very low profile - typical height of 1.7 mm
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection.

## MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** As marked

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 15.0 A
$V_{RRM}$	170 V
$I_{FSM}$	260 A
$V_F$ at $I_F = 5.0$ A ( $T_A = 125$ °C)	0.66 V
$T_J$ max.	175 °C
Package	SMPD (TO-263AC)
Circuit configurations	Common cathode

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V30D170C	UNIT
Device marking code		V30D170C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	170	V
Maximum average forward rectified current (fig. 1)	per device	30	A
	per diode	15	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	260	A
Operating junction temperature range	$T_J$ <sup>(1)</sup>	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	°C

### Note

<sup>(1)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	$I_F = 5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.72	-	V
	$I_F = 10\text{ A}$			0.78	-	
	$I_F = 15\text{ A}$			0.8	0.88	
	$I_F = 5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.56	-	
	$I_F = 10\text{ A}$			0.64	-	
	$I_F = 15\text{ A}$			0.66	0.73	
Reverse current at rated $V_R$ per diode	$V_R = 140\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.01	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		1.5	-	mA
	$V_R = 170\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.2	mA
		$T_A = 125\text{ }^\circ\text{C}$		3	10	mA
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	1200	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: Pulse width  $\leq 5\text{ ms}$

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V30D170C	UNIT
Typical thermal resistance per device	$R_{\theta JC}^{(1)}$	1.1	$^\circ\text{C/W}$
	$R_{\theta JA}^{(2)(3)}$	50	

**Notes**

- (1) Mounted on infinite heatsink  
 (2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-mount  
 (3) Free air, without heatsink

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V30D170C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
V30D170CHM3/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

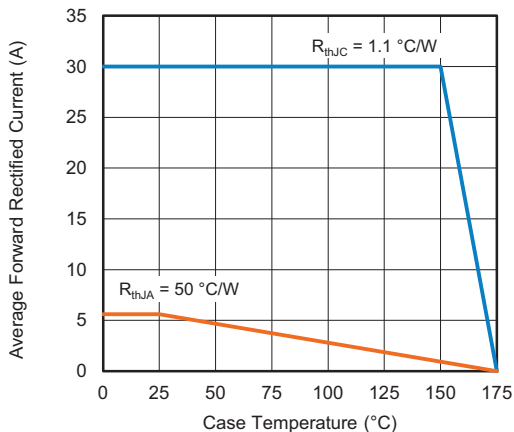
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

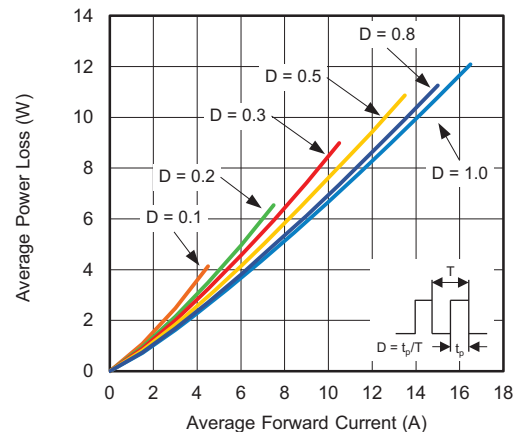


Fig. 2 - Forward Power Loss Characteristics

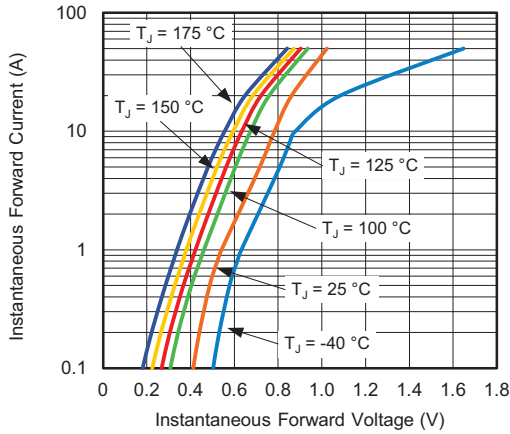


Fig. 3 - Typical Instantaneous Forward Characteristics

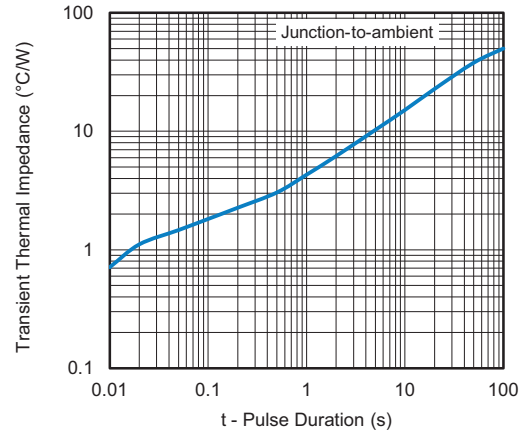


Fig. 6 - Typical Transient Thermal Impedance

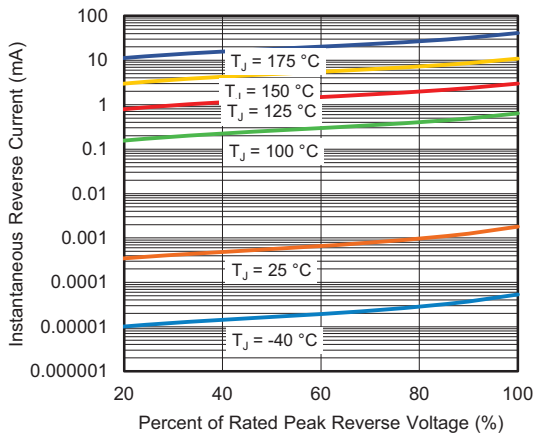


Fig. 4 - Typical Reverse Characteristics

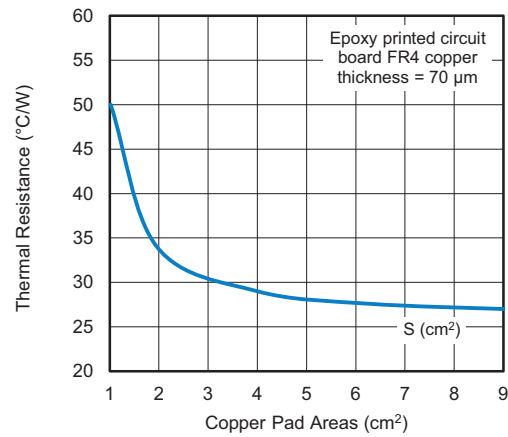


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

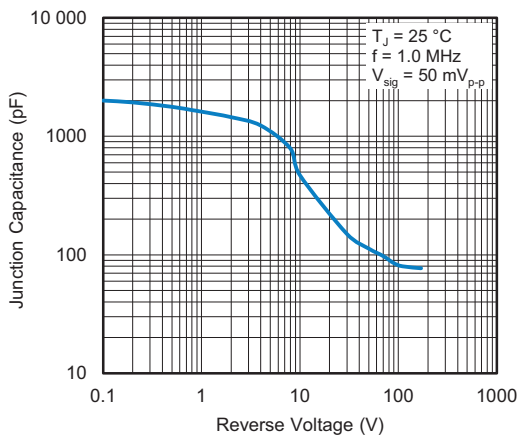
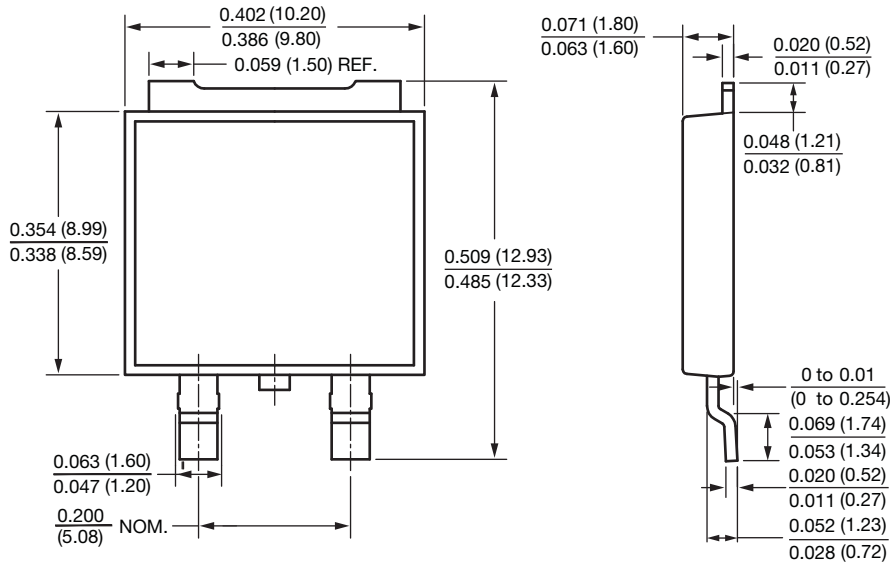


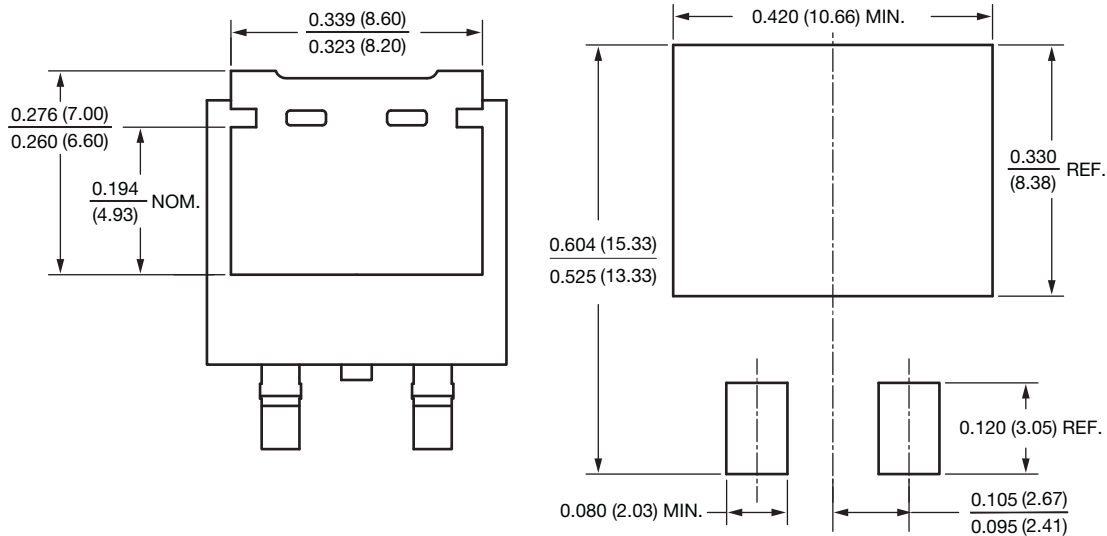
Fig. 5 - Typical Junction Capacitance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**SMPD (TO-263AC)**



**Mounting Pad Layout**





## Disclaimer

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